

## High Speed Infrared Emitting Diodes, 890 nm, Surface Emitter Technology



### DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY5890 is an infrared, 890 nm emitting diode based on GaAlAs surface emitter chip technology with high radiant intensity, high optical power and high speed, in a low profile 0805 surface mount (SMD) package.

### FEATURES

- Package type: surface-mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.8
- Peak wavelength:  $\lambda_p = 890$  nm
- High speed
- Angle of half intensity:  $\phi = \pm 60^\circ$
- 0805 standard surface-mountable package
- Floor life: 168 h, MSL 3, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?999912](http://www.vishay.com/doc?999912)



### APPLICATIONS

- Miniature light barrier
- Optical switch
- IR point source

### PRODUCT SUMMARY

COMPONENT	$I_e$ (mW/sr) at $I_F = 100$ mA	$\phi$ (°)	$\lambda_p$ (nm)	$t_r$ (ns)
VSMY5890	13	$\pm 60$	890	7

#### Note

- Test conditions see table “Basic Characteristics“

### ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY5890	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

#### Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	100	mA
Peak forward current	$t_p/T = 0.1, t_p = 100\text{ }\mu\text{s}$	$I_{FM}$	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	$I_{FSM}$	500	mA
Power dissipation		$P_V$	210	mW
Junction temperature		$T_j$	125	$^{\circ}\text{C}$
Operating temperature range		$T_{amb}$	-40 to +110	$^{\circ}\text{C}$
Storage temperature range		$T_{stg}$	-40 to +110	$^{\circ}\text{C}$
Soldering temperature	According to Fig. 7, J-STD-020	$T_{sd}$	260	$^{\circ}\text{C}$
Thermal resistance junction-to-ambient	EIA / JESD51	$R_{thJA}$	280	K/W

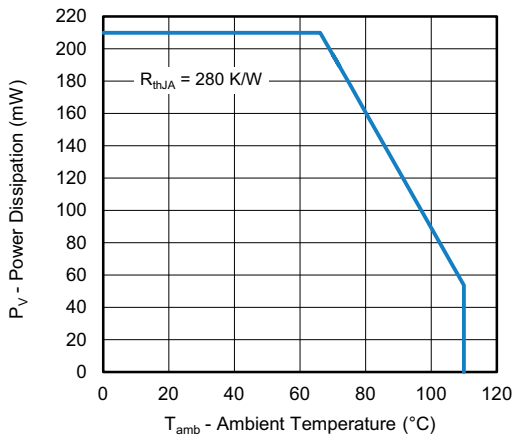


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

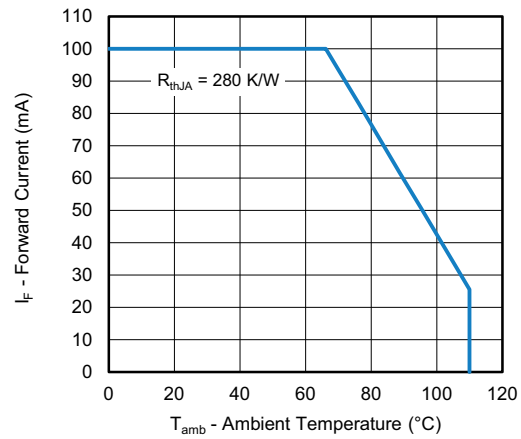


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$V_F$	-	1.8	2.1	V
Temperature coefficient of $V_F$	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$TK_{V_F}$	-	-1.6	-	mV/K
Reverse current		$I_R$	Not designed for reverse operation			$\mu\text{A}$
Junction capacitance	$V_R = 0\text{ V}, f = 1\text{ MHz}, E = 0\text{ mW/cm}^2$	$C_J$	-	30	-	pF
Radiant intensity	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$I_e$	10	13	18	mW/sr
Temperature coefficient of radiant power	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$TK_{\phi_e}$	-	-0.2	-	%/K
Angle of half intensity		$\phi$	-	$\pm 60$	-	$^{\circ}$
Peak wavelength	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$\lambda_p$	-	890	-	nm
Spectral bandwidth	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$\Delta\lambda$	-	40	-	nm
Temperature coefficient of $\lambda_p$	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$TK_{\lambda_p}$	-	0.25	-	nm/K
Rise time	$I_F = 100\text{ mA}, 10\% \text{ to } 90\%$	$t_r$	-	8	-	ns
Fall time	$I_F = 100\text{ mA}, 10\% \text{ to } 90\%$	$t_f$	-	8	-	ns

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

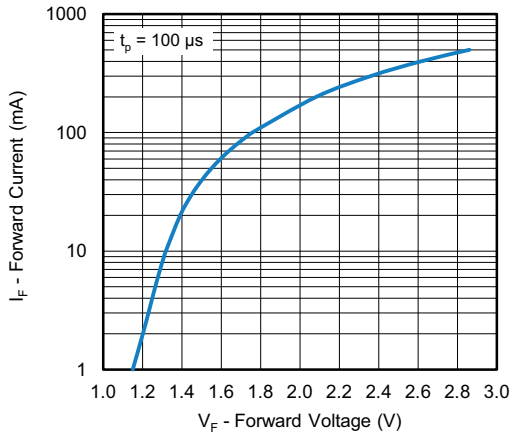


Fig. 3 - Forward Current vs. Forward Voltage

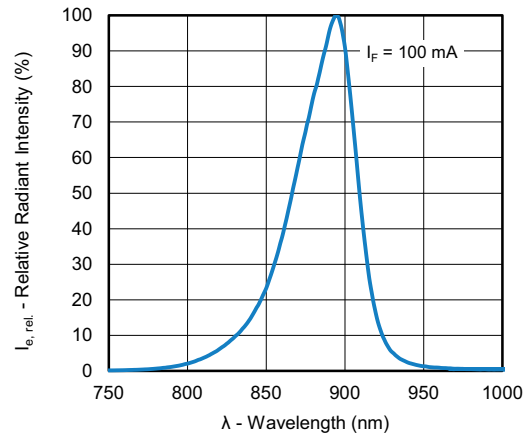


Fig. 5 - Relative Radiant Power vs. Wavelength

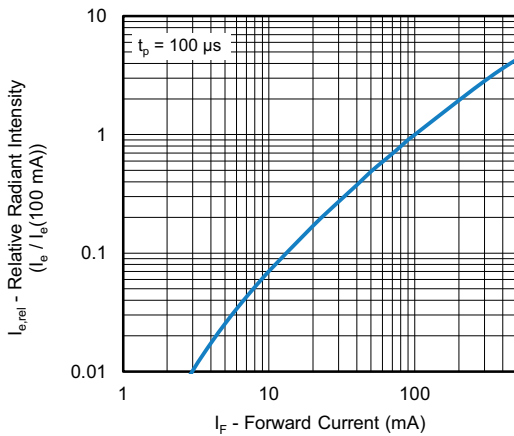


Fig. 4 - Relative Radiant Intensity vs. Forward Current

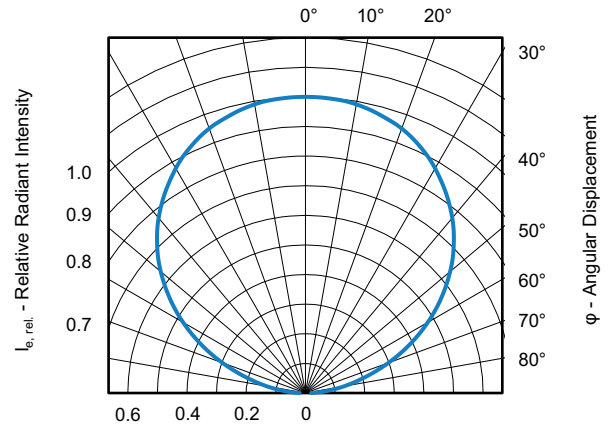


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

**REFLOW SOLDER PROFILE**



19841

Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

**DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

**FLOOR LIFE**

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

Conditions:  $T_{amb} < 30\text{ }^{\circ}\text{C}$ , RH < 60 %

**DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-033D or label. Devices taped on reel dry using recommended conditions 192 h at  $40\text{ }^{\circ}\text{C}$  (+ 5 °C), RH < 5 %.

**PACKAGE DIMENSIONS** in millimeters



Drawing- No.: 6.550-5352.01-4  
 Issue: 1; 20.12.2016

**BLISTER TAPE DIMENSIONS** in millimeters



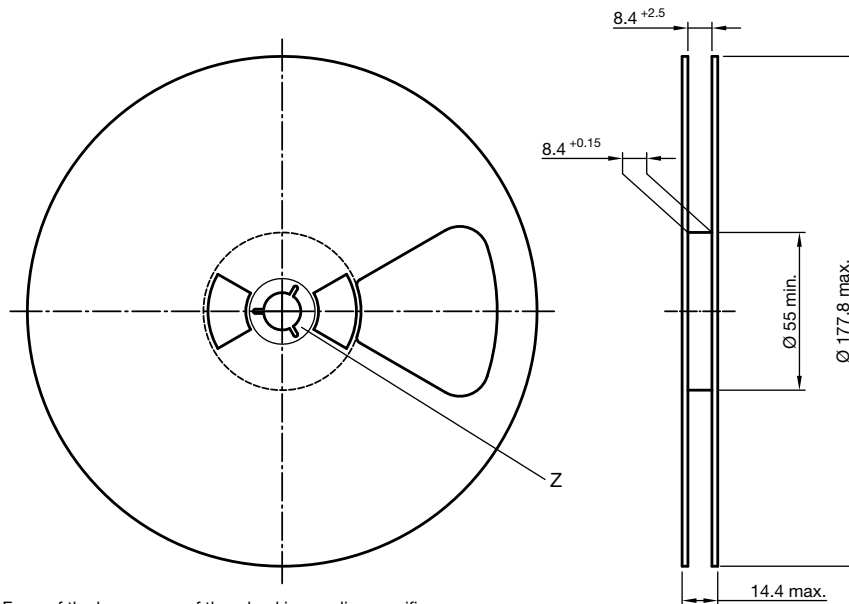
Not indicated tolerances ± 0.1



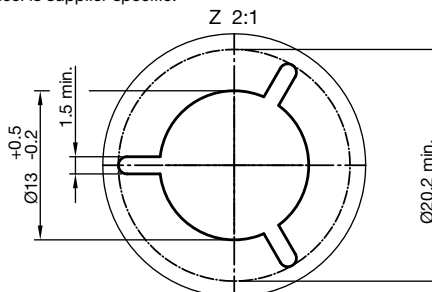
Technical drawings according to DIN specification.

Drawing-No.: 9.700-5352.02-4  
Issue: 1; 20.12.2016

**REEL DIMENSIONS** in millimeters



Form of the leave open of the wheel is supplier specific.



Technical drawings according to DIN specification.

Drawing-No.: 9.800-5096.01-4  
Issue: 5; 20.12.2016



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